A. FURTHER INFORMATION ABOUT OUR GROUP

1. Incorporation of our Company

Our Company was incorporated in the PRC on July 11, 2000 and was converted into a joint stock limited company on April 28, 2008. Our Company completed the listing of A Shares on the ChiNext of the Shenzhen Stock Exchange (stock code: 300054) on February 11, 2010.

As of the date of this document, our Company's registered address and headquarters were located at No. 1 Dongjinghe Road, Wuhan Economic and Technological Development Zone, Wuhan, Hubei Province, the PRC. Our Company's corporate structure and Articles of Association are governed by PRC laws and regulations.

Our registered place of business in Hong Kong is at 31/F, Tower Two Times Square, 1 Matheson Street, Causeway Bay, Hong Kong. We have been registered as a non-Hong Kong Company under Part 16 of the Companies Ordinance on April 8, 2026. Ms. Fung Sin Ting Karin (馮羨婷) has been appointed as the authorized representative of our Company for the acceptance of the service of process on behalf of our Company in Hong Kong. The address for the service of process is the same as our principal place of business in Hong Kong.

2. Changes in the Share Capital of Our Company

Save as disclosed below and the section headed "History and Corporate Structure," there has been no alteration in the share capital of our Company within two years immediately preceding the date of this document.

(i) From May 2025 to June 2026, due to the exercise of the stock options under the 2024 Stock Option Incentive Plan, the total share capital of our Company increased by 14,960,889 A Shares.

(ii) From October 2025 to June 2026, due to conversion of an aggregate of 4,356 Convertible Bonds, the total share capital of our Company increased by 15,201 A Shares.

3. Changes in the Share Capital of Our Subsidiaries

A summary of the corporate information and the particulars of our principal subsidiaries are set out in Note I to the Accountants' Report in Appendix I to this document.

(i) On April 2, 2025, the registered capital of Dinglong Huisheng increased from RMB20 million to RMB200 million.

(ii) On September 26, 2025, the registered capital of Rouxian (Xiantao) Photoelectric Semiconductor increased from RMB80 million to RMB160 million.

(iii) On September 29, 2025, the registered capital of Dinglong (Xiantao) New Materials increased from RMB100 million to RMB220 million.

(iv) On October 27, 2025, the registered capital of Dinglong New Materials increased from RMB20 million to RMB70 million.

(v) On February 23, 2026, the registered capital of DINGTEK (MALAYSIA) SDN. BHD. increased from RM47 million to RM51 million.

(vi) On May 27, 2026, the registered capital of Wuhan Aotesaide Technology Co., Ltd. (武漢奧特賽德科技有限公司) decreased from RMB300 million to RMB30 million.

Save as disclosed above, there has been no alteration in the share capital of any of our subsidiaries during the two years immediately preceding the date of this document.

4. Shareholders' Resolutions

Pursuant to the Shareholders' general meeting held on April 24, 2026, the following resolutions, among others, were duly passed:

(i) the [REDACTED] of H Shares with a nominal value of RMB1.00 each by our Company and such H Shares be [REDACTED] on the Stock Exchange;

(ii) the number of H Shares to be issued before the exercise of the [REDACTED] pursuant to the [REDACTED] shall not exceed [REDACTED]% of the enlarged share capital of our Company upon completion of the [REDACTED], and the [REDACTED] shall not exceed [REDACTED]% of the total number of H Shares to be [REDACTED] initially under the [REDACTED];

(iii) subject to the completion of the [REDACTED], the Articles of Association to become effective on the [REDACTED] shall be conditionally adopted, and the Board and its authorized person have been authorized to amend the Articles of Association in accordance with any comments from the relevant regulatory authorities; and

(iv) to authorize the Board and its authorized person to handle the matters relating to, among others, the [REDACTED], the [REDACTED] and [REDACTED] of the H Shares.

B. FURTHER INFORMATION ABOUT OUR BUSINESS

1. Summary of Material Contract

We [have entered] into the following contract (not being contracts entered into in the ordinary course of business) within the two years immediately preceding the date of this document that is or may be material:

(i) [REDACTED].

2. Intellectual Property Rights

(i) Trademarks

(a) Registered Trademarks

As of the Latest Practicable Date, we had registered the following trademarks which we consider to be or may be material to our business:

No.	Trademark	Place of Registration	Registered Owner	Class	Registration Number	Expiry Date
1.	DINGLONG	PRC	Our Company	5	18248897	February 13, 2037
2.	DINGLONG	PRC	Our Company	38	18248900	February 6, 2037
3.	DINGLONG	PRC	Our Company	40	18248899	February 6, 2037
4.	DINGLONG	PRC	Our Company	1, 2, 9, 17	51365733	January 27, 2032
5.	DINGLONG	PRC	Our Company	3	34112683	August 6, 2029
6.		PRC	Our Company	10	18248898	December 13, 2036
7.		PRC	Our Company	2, 9, 16	67269977	March 13, 2033
8.		PRC	Our Company	16	21408816	November 20, 2027
9.	DINGLONG	PRC	Our Company	7	20192881	October 13, 2027
10.	DK	PRC	Our Company, Dinghui Microelectronics	7	47875729	February 20, 2031
11.	DK	PRC	Our Company, Dinghui Microelectronics	35	47877464	February 20, 2031

No.	Trademark	Place of Registration	Registered Owner	Class	Registration Number	Expiry Date
12.		PRC	Our Company, Dinghui Microelectronics	7	47859066	February 20, 2031
13.		PRC	Our Company, Dinghui Microelectronics	35	47886523	February 20, 2031
14.	ROUXIAN	PRC	Our Company, Rouxian Science and Technology	1	31997703	July 13, 2029
15.	ROUXIAN	PRC	Our Company, Rouxian Science and Technology	2	32726459	June 13, 2029
16.	柔显科技	PRC	Rouxian Science and Technology	2	45958365	February 6, 2032
17.	柔显科技	PRC	Rouxian Science and Technology	2, 9, 17, 35	45986180A	March 13, 2031
18.		PRC	Rouxian Science and Technology	1–2, 9, 17, 35	51234203A	August 27, 2031
19.		PRC	Rouxian Science and Technology	1–2, 9, 17, 35	51242013A	August 27, 2031
20.	Chipjet	Brazil; Vietnam	Qijie Technology	9	1617569	August 13, 2031
21.	Chipjet	the United States	Qijie Technology	2, 9	6213434	December 8, 2030
22.	Chipjet	Japan	Qijie Technology	2, 16, 35	6279522	August 12, 2030
23.	Chipjet	Japan	Qijie Technology	9	6234764	March 11, 2030
24.	Chipjet	European Union; the United Kingdom; the United States; Russia	Qijie Technology	2, 9	1474960	December 17, 2028
25.	Chipjet	PRC	Qijie Technology	2	20756524	September 20, 2027
26.	Chipjet	PRC	Qijie Technology	9	20756885	September 13, 2027

No.	Trademark	Place of Registration	Registered Owner	Class	Registration Number	Expiry Date
27.	Chipjet	PRC	Qijie Technology	42	20757166	September 20, 2027
28.	旗捷	PRC	Qijie Technology	9	6924961	August 6, 2030
29.	旗捷	PRC	Qijie Technology	2	18731125	February 6, 2027
30.	旗捷	PRC	Qijie Technology	42	18731451	February 6, 2027
31.	旗捷	PRC	Qijie Technology	9	20756290	September 13, 2027
32.	旗捷	PRC	Qijie Technology	2	20756267	September 13, 2027
33.	旗捷	PRC	Qijie Technology	42	20756838	September 13, 2027

(b) Trademark under Application

As of the Latest Practicable Date, we had applied for registration of the following trademark which we consider to be or may be material to our business:

No.	Trademark	Applicant	Class	Place of Application	Application Date	Application Number
1	DINGLONG DINGLONG	Our Company	1, 2, 3, 7, 9, 16, 17, 35	Hong Kong	March 18, 2026	307220295

(ii) Patents

(a) Registered Patents

As of the Latest Practicable Date, we owned the following registered patents which we consider to be or may be material to our business:

No.	Owner	Patent	Type of Patent	Patent Number	Application Date	Expiry Date	Place of Registration
1.	Our Company	A Polishing Pad and Method for Preparing the Same (一種拋光墊及用於製備拋光墊的方法)	Invention	CN201711353073.9	December 15, 2017	December 14, 2037	PRC
2.	Our Company	Weather-resistant Polishing Pad (耐候性拋光墊)	Invention	US15/233922	August 10, 2016	March 27, 2037	the United States
3.	Our Company	A Polishing Pad (一種拋光墊)	Invention	CN201611011643.1	November 17, 2016	November 16, 2036	PRC
4.	Our Company	Detection Window for Chemical Mechanical Polishing Pad and Preparation Method Thereof (化學機械拋光墊的檢測窗及其製備方法)	Invention	CN201610390615.9	June 3, 2016	June 2, 2036	PRC
5.	Our Company	Synthesis Method of Polyimide (一種聚醯亞胺的合成方法)	Invention	CN201510733059.6	November 2, 2015	November 1, 2035	PRC
6.	Our Company	Acrylic Resin, Carrier Coated Therewith, and Two-component Developer (丙烯酸樹脂和用該樹脂包覆的載體、及雙組分顯影劑)	Invention	CN201510700240.7	October 23, 2015	October 22, 2035	PRC
7.	Our Company	Colored Toner and Method for Preparing the Same (彩色碳粉及其製備方法)	Invention	US13/845153	March 18, 2013	April 15, 2033	the United States
8.	Our Company	Manufacturing Method of Carrier for Electrostatic Image Developer (靜電圖像顯影劑用載體的製造方法)	Invention	CN201210052732.6	March 2, 2012	March 1, 2032	PRC
9.	Our Company	Bicomponent Developing Agent (雙組分顯影劑)	Invention	US13/178496	July 8, 2011	June 12, 2031	the United States
10.	Our Company	Color Toner and Preparation Method Thereof (彩色碳粉及其製備方法)	Invention	EP2010734886	May 4, 2010	May 3, 2030	Europe

No.	Owner	Patent	Type of Patent	Patent Number	Application Date	Expiry Date	Place of Registration
11.	Our Company	Manufacturing Method of Toner for Electrostatic Charge Development (靜電荷顯影用碳粉的製造方法)	Invention	CN200810048434.3	July 17, 2008	July 16, 2028	PRC
12.	Our Company	Toner for Electrostatic Charge Development and Manufacturing Method Thereof (靜電荷顯影用碳粉及其製造方法)	Invention	CN200810047016.2	March 6, 2008	March 5, 2028	PRC
13.	Our Company; Dinglong Xinsheng Technology; Dinglong (Qianjiang) New Materials; Dinghui Microelectronics	Fluorine-containing Resin Powder, Photoresist Composition Containing the Same, and Preparation Method and Application Thereof (一種含氟樹脂粉末、包含其的光致抗蝕劑組合物及其製備方法和應用)	Invention	CN202511205103.6	August 27, 2025	August 26, 2045	PRC
14.	Our Company; Dingze (Xiantao); Dingze New Materials Technology; Dinglong (Xiantao) New Materials	Manufacturing Method of Semiconductor Device, Silica Sol, Preparation Method Thereof, and Polishing Composition (半導體器件的製造方法、硅溶膠及其製備方法和研磨用組合物)	Invention	CN202510163022.8	February 14, 2025	February 13, 2045	PRC
15.	Our Company; Dinghui Microelectronics; Dinglong Huisheng	Polishing Layer, Polishing Pad and Polishing Method (拋光層，拋光墊及拋光方法)	Invention	CN202510005327.6	January 2, 2025	January 1, 2045	PRC
16.	Our Company; Dingze New Materials Technology; Dinghui Microelectronics	Cleaning Composition After Chemical Mechanical Polishing and Cleaning Method for Semiconductor Device Substrate (化學機械拋光後清洗組合物及半導體器件基板的清洗方法)	Invention	CN202310501171.1	April 28, 2023	April 27, 2043	PRC
17.	Our Company; Dinghui Microelectronics; Dingze New Materials Technology	A Polishing Pad (一種拋光墊)	Invention	CN202111506323.4	December 10, 2021	December 9, 2041	PRC

No.	Owner	Patent	Type of Patent	Patent Number	Application Date	Expiry Date	Place of Registration
18.	Our Company; Dinghui Microelectronics; Changxin Memory Technologies, Inc. (長鑫存儲技術有限公司)	A Polishing Pad (一種拋光墊)	Invention	CN202110087557.3	January 22, 2021	January 21, 2041	PRC
19.	Our Company; Rouxian Science and Technology	Polyimide Precursor, Polyimide Film and Preparation Method Thereof and Display Device (聚醯亞胺前體、聚醯亞胺薄膜及其製備方法以及顯示裝置)	Invention	CN202011456977.6	December 10, 2020	December 9, 2040	PRC
20.	Our Company; Rouxian Science and Technology	Preparation Method of Polyimide Copolymer Precursor, Polyimide and Polyimide Film (聚醯亞胺共聚物前體、聚醯亞胺以及聚醯亞胺薄膜的製備方法)	Invention	CN201811563637.6	December 20, 2018	December 19, 2038	PRC
21.	Our Company; Dinglong Huisheng; Dinghui Microelectronics; Dingze New Materials Technology	Polishing Pad and Grinding Equipment (拋光墊及研磨設備)	Invention	CN201810738877.9	July 6, 2018	July 5, 2038	PRC
22.	Our Company; Dinghui Microelectronics	Polishing Pad and Manufacturing Method of Semiconductor Device (拋光墊及半導體元件的製造方法)	Invention	KR1020220117559	September 19, 2022	September 18, 2042	South Korea
23.	Our Company; Dinghui Microelectronics	Preparation Method of Polishing Pad (拋光墊的製備方法)	Invention	CN201810528347.1	May 28, 2018	May 27, 2038	PRC
24.	Dinghui Microelectronics	Polishing Pad and Manufacturing Method of Semiconductor Device (拋光墊及半導體元件的製造方法)	Invention	TW112145705	November 24, 2023	November 22, 2043	Taiwan, PRC
25.	Dinghui Microelectronics	Polishing Pad, Polishing Layer, Polyamine Composition (拋光墊、拋光層、多元胺組合物)	Invention	TW112115391	April 25, 2023	April 23, 2043	Taiwan, PRC

No.	Owner	Patent	Type of Patent	Patent Number	Application Date	Expiry Date	Place of Registration
26.	Dinghui Microelectronics	CMP layer based on porous cerium oxide and preparation method thereof (基於多孔氧化鈰之化學機械研磨層及其製備方法)	Invention	US16/186575	November 11, 2018	May 20, 2039	the United States
27.	Dinghui Microelectronics	Polyurethane Polishing Layer, Polishing Pad Comprising Polishing Layer, Manufacturing Method of Polishing Layer and Material Planarization Method (聚胺酯研磨層、含研磨層之研磨墊、研磨層之製造方法及材料平坦化方法)	Invention	KR1020207005721	August 31, 2018	August 30, 2038	South Korea
28.	Dinghui Microelectronics	A Grinding and Polishing Method for Ultra-hard Brittle Workpieces (一種超硬脆工件的研磨拋光方法)	Invention	CN201610857938.4	September 28, 2016	September 27, 2036	PRC
29.	Qijie Technology	Consumable Chip, Consumable Cartridge Having the Same, and Manufacturing Method Thereof (耗材芯片、具有其的耗材盒以及耗材芯片的製作方法)	Invention	US18/098715	January 19, 2023	July 17, 2042	the United States
30.	Qijie Technology	Cartridge Test Device, Cartridge Component, and Cartridge Component Test Method (墨盒測試設備、墨盒組件及墨盒組件測試方法)	Invention	US17/861262	July 11, 2022	September 1, 2041	the United States
31.	Qijie Technology	Method for Controlling Regenerated Chip, Regenerated Chip and Regenerated Ink Cartridge (再生芯片的控制方法、再生芯片和再生墨盒)	Invention	EP2021822814	April 2, 2021	April 1, 2041	Europe
32.	Qijie Technology	Repair Chip, Ink Cartridge, and Printer (修復芯片、墨盒和打印機)	Invention	EP2020899508	December 11, 2020	December 10, 2040	Europe

No.	Owner	Patent	Type of Patent	Patent Number	Application Date	Expiry Date	Place of Registration
33.	Qijie Technology	Communication Method for Consumables Chip, Consumables Chip, and Consumable (一種耗材芯片通信方法、耗材芯片及耗材)	Invention	US17/441277	June 17, 2020	August 7, 2040	the United States
34.	Qijie Technology	Automatic Reset Method for Consumable Chip, and Consumable Chip (耗材芯片的自動復位方法、耗材芯片)	Invention	EP2020822275	April 27, 2020	April 26, 2040	Europe
35.	Qijie Technology	Consumable Chip, and Consumable Chip Communication Method (一種耗材芯片、耗材芯片通信方法)	Invention	EP2020745015	January 13, 2020	January 12, 2040	Europe
36.	Qijie Technology	Consumable Chip, Consumable and Consumable Communication Method (耗材芯片、耗材、耗材通信方法)	Invention	US16/475880	August 10, 2018	August 9, 2038	the United States
37.	Qijie Technology	Consumable Chip Data Rewriting Device (耗材芯片數據改寫設備)	Invention	EP2017915974	July 19, 2017	July 18, 2037	Europe
38.	Qijie Technology	Recycled Ink Cartridge, Recycled Chip, Printer System Communication Method, and Ink Cartridge Recycling Method (再生墨盒、再生芯片、打印機系統通信方法、墨盒再生方法)	Invention	EP2016891986	March 2, 2016	March 1, 2036	Europe
39.	Qijie Technology	Repair Method and Repair Chip for Remanufactured Ink Cartridge, and Remanufactured Ink Cartridge (再生墨盒的修復方法、修復芯片和再生墨盒)	Invention	EP2015911044	December 22, 2015	December 21, 2035	Europe
40.	Qijie Technology	Repair Method, Repair Chip and Regenerated Ink Cartridge (再生墨盒的修復方法、修復芯片和再生墨盒)	Invention	CN201510966214.9	December 22, 2015	December 21, 2035	PRC

(b) Patents under Application

As of the Latest Practicable Date, we had applied for the registration of the following patents which we consider to be or may be material to our business:

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
1.	Our Company	Multi-layer Core-shell Structure Chemical Toner and Its Preparation Method (多層核殼結構化學碳粉及其製備方法)	Invention	CN202511212649.4	August 28, 2025	PRC
2.	Our Company; Dinglong Huisheng; Dinghui Microelectronics	Chemical Mechanical Polishing Pad and Its Preparation Method (化學機械拋光墊及其製備方法)	Invention	CN202511853462.2	December 10, 2025	PRC
3.	Our Company; Dinglong Huisheng; Dinghui Microelectronics	Buffer Layer of Chemical Mechanical Polishing Pad, Preparation Method, Polishing Pad and Application (化學機械拋光墊緩衝層、製備方法、拋光墊及應用)	Invention	CN202511648191.7	November 12, 2025	PRC
4.	Our Company; Rouxian Science and Technology; Rouxian (Xiantao) Photoelectric Semiconductor	Photosensitive Resin Composition, Cured Film and Color Light-Shielding Layer (感光樹脂組合物、固化膜和彩色遮光層)	Invention	CN202511340603.0	September 19, 2025	PRC
5.	Our Company; Rouxian Science and Technology; Rouxian (Xiantao) Photoelectric Semiconductor	Photosensitive Resin Composition, Cured Film, Patterned Cured Film and Its Application (感光樹脂組合物、固化膜、圖案固化膜及其應用)	Invention	CN202511233007.2	September 1, 2025	PRC
6.	Our Company; Rouxian Science and Technology; Rouxian (Xiantao) Photoelectric Semiconductor	Liquid Crystal Alignment Agent, Liquid Crystal Alignment Film and Liquid Crystal Display Element (一種液晶取向劑、液晶取向膜和液晶表示元件)	Invention	CN202510880408.0	June 27, 2025	PRC

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
7.	Our Company; Dinglong (Qianjiang) New Materials; Dinglong Xinsheng Technology	Sulfonium Salt Compound, Resist Composition and Pattern Formation Method (鋶鹽化合物、抗蝕劑組合物及圖案形成方法)	Invention	CN202510664964.4	May 22, 2025	PRC
8.	Our Company; Dingze New Materials Technology; Dingze (Xiantao); Dinglong (Xiantao) New Materials	Chemical Mechanical Polishing Composition for Polysilicon and Polishing Method (一種用於多晶硅的化學機械拋光組合物、拋光方法)	Invention	CN202510476194.0	April 16, 2025	PRC
9.	Our Company; Dingze New Materials Technology; Dingze (Xiantao); Dinglong New Materials	Cerium Oxide Powder, Preparation Method and Chemical Mechanical Polishing Slurry (一種氧化鈰粉體、製備方法及化學機械拋光液)	Invention	CN202510436429.3	April 9, 2025	PRC
10.	Our Company; Dingze New Materials Technology; Dingze (Xiantao); Dinglong New Materials	Acidic Aluminum Oxide Polishing Composition for Silicon Carbide Substrate Rough Polishing and Polishing Method (一種碳化矽襯底粗拋用酸性氧化鋁拋光組合物及拋光方法)	Invention	CN202510399868.1	April 1, 2025	PRC
11.	Our Company; Dinglong Xinsheng Technology; Dinglong (Qianjiang) New Materials; Dinghui Microelectronics	A Photoresist Composition and Pattern-forming Method Thereof (一種光致抗蝕劑組合物及其圖案形成方法)	Invention	CN202411898423.X	December 23, 2024	PRC
12.	Our Company; Dinghui Microelectronics; Dinglong (Xiantao) New Materials	Thermal Expandable Microspheres and Preparation Method Thereof (一種熱膨脹微球及其製備方法)	Invention	CN202411804315.1	December 10, 2024	PRC

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
13.	Our Company; Dinglong (Qianjiang) New Materials; Dinglong Xinsheng Technology	Onium Salt Compound, Photo-induced Acid Generator, Photoresist Composition Comprising the Same (鎓鹽類化合物、光致產酸劑、包含其的光致抗蝕劑組合物)	Invention	CN202410644528.6	May 23, 2024	PRC
14.	Our Company; Dingze New Materials Technology	Cleaning Composition After Chemical Mechanical Polishing and Cleaning Method (化學機械拋光後清洗組合物及清洗方法)	Invention	CN202410518901.3	April 28, 2024	PRC
15.	Our Company; Rouxian Science and Technology	Photosensitive Resin Composition, Method for Producing Patterned Cured Film, Cured Film and Application Thereof (感光樹脂組合物、圖案固化膜的製造方法、固化膜及其應用)	Invention	CN202310792181.5	June 29, 2023	PRC
16.	Our Company; Dinghui Microelectronics; Dinglong Huisheng	Detection Window, Polishing Pad and Polishing System (檢測窗口、拋光墊及拋光系統)	Invention	CN202310538633.7	May 15, 2023	PRC
17.	Qijie Technology	Chip and Control Method Thereof (芯片及其控制方法)	Invention	CN202511556018.4	October 28, 2025	PRC
18.	Qijie Technology	Chip Short-Circuit Check Method and Apparatus, Chip Testing Method, Chip and Consumable Box (芯片短路校驗方法、裝置、芯片檢測方法、芯片和耗材盒)	Invention	EP2024777822	March 20, 2024	Europe

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
19.	Qijie Technology	Chip Short-Circuit Check Method and Apparatus, Chip Testing Method, Chip and Consumable Box (芯片短路校驗方法、裝置、芯片檢測方法、芯片和耗材盒)	Invention	JP2025556693	March 20, 2024	Japan
20.	Qijie Technology	Chip Short-Circuit Check Method and Apparatus, Chip Testing Method, Chip and Consumable Box (芯片短路校驗方法、裝置、芯片檢測方法、芯片和耗材盒)	Invention	US19/339871	September 25, 2025	the United States
21.	Qijie Technology	Upgrade Method, Apparatus, Upgrade Device and Upgrade System (一種升級方法、裝置、升級設備及升級系統)	Invention	CN202511323957.4	September 16, 2025	PRC
22.	Qijie Technology	Printing Consumable Device, Printing Consumable and Communication Method for Printing Consumable Device (打印耗材裝置、打印耗材和打印耗材裝置通訊方法)	Invention	CN202511312801.6	September 12, 2025	PRC
23.	Qijie Technology	Consumable Chip, Consumable Cartridge Having the Same, and Manufacturing Method Thereof (耗材芯片、具有其的耗材盒以及耗材芯片的製作方法)	Invention	US19/169053	April 3, 2025	the United States
24.	Qijie Technology	Data Storage Method, Apparatus, Device, Storage Medium, Computer Program Product (數據存儲方法、裝置、設備、存儲介質、計算機程序產品)	Invention	CN202411533216.4	October 30, 2024	PRC

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
25.	Qijie Technology	Consumable Chip, Consumable Chip Control Method and Printing Consumable (耗材晶片、耗材晶片控制方法和打印耗材)	Invention	CN202411449339.X	October 16, 2024	PRC
26.	Qijie Technology	Clock Control Method, Security Chip, Device and Storage Medium (一種時鐘控制方法、安全晶片、設備及存儲介質)	Invention	CN202410398612.4	April 2, 2024	PRC
27.	Qijie Technology	Consumable Authentication Method, Apparatus, System, Consumable Chip and Printing Consumable (耗材認證方法、裝置、系統、耗材晶片及打印耗材)	Invention	CN202410211621.8	February 26, 2024	PRC
28.	Qijie Technology	Firmware Upgrade Method, Apparatus, System, Device and Storage Medium (固件升級方法、裝置、系統、設備及存儲介質)	Invention	CN202410095124.6	January 23, 2024	PRC
29.	Qijie Technology	Consumable Chip, Working Method and Consumable Box (耗材晶片、工作方法及耗材盒)	Invention	CN202311843202.8	December 27, 2023	PRC
30.	Qijie Technology	Chip Short-Circuit Check Method and Apparatus, Chip Testing Method, Chip and Consumable Box (晶片短路校驗方法、裝置、晶片檢測方法、晶片和耗材盒)	Invention	CN202311737080.4	December 15, 2023	PRC
31.	Qijie Technology	Chip Short-Circuit Check Method, Chip and Ink Cartridge (晶片短路校驗方法、晶片和墨水匣)	Invention	CN202310882117.6	July 18, 2023	PRC

No.	Applicant	Patent	Type of Patent	Application Number	Application Date	Place of Registration
32.	Qijie Technology	Authentication Method, Authentication Apparatus and System (認證方法、認證裝置與系統)	Invention	CN202310683803.0	June 8, 2023	PRC
33.	Qijie Technology	Secure Communication Method, Chip, Device and Readable Storage Medium (安全通訊方法、晶片、設備及可讀存儲介質)	Invention	CN202310456661.4	April 24, 2023	PRC
34.	Qijie Technology	Clock Frequency Detection Circuit and Chip (時鐘頻率檢測電路及晶片)	Invention	CN202310436342.7	April 17, 2023	PRC
35.	Qijie Technology	Consumable Chip, Consumable Cartridge Having the Same, and Manufacturing Method Thereof (耗材芯片、具有其的耗材盒以及耗材芯片的製作方法)	Invention	EP2022844821	January 29, 2022	Europe
36.	Qijie Technology	Printer Consumable Chip Upgrade System and Method, and Consumable Container (打印機耗材芯片升級系統、方法以及耗材容器)	Invention	EP2021745077	January 20, 2021	Europe
37.	Qijie Technology	Communication Method for Consumable Chip, Consumable Chip and Consumable (一種耗材晶片通訊方法、耗材晶片及耗材)	Invention	CN201910635752.8	July 15, 2019	PRC

(iii) Copyrights

As of the Latest Practicable Date, we were the registered proprietors of the following software copyrights which we consider to be or may be material to our business:

No.	Software	Owner	Registration Number	Place of Registration
1.	Dinglong Intelligent Industrial Park Management System Software (鼎龍智慧園區系統軟件)	Our Company	2024SR0027540	PRC
2.	Qijie Passive RF Tag Mass Production System Software (旗捷無源RF標籤量產系統軟件)	Qijie Technology	2025SR0203121	PRC
3.	Qijie Dynamic Data Signature Software for Hardware Security (旗捷硬件安全領域的動態數據簽名軟件)	Qijie Technology	2025SR0620052	PRC
4.	Qijie Chip Dynamic Power Consumption Control Software (旗捷芯片動態功耗控制功耗軟件)	Qijie Technology	2025SR0701356	PRC
5.	Qijie High-speed Code Automatic Generation Software Based on AHB Bus (旗捷基於AHB總線高速代碼自動生成軟件)	Qijie Technology	2024SR0165872	PRC
6.	Qijie Printing Consumable Chip Test Analysis Software (旗捷打印耗材芯片測試解析軟件)	Qijie Technology	2024SR0960249	PRC
7.	Qijie Chip Data Wireless Upgrade Software (旗捷芯片數據無線升級軟件)	Qijie Technology	2024SR1269658	PRC
8.	Qijie Data Signature Software for Hardware Security Field (旗捷硬件安全領域的數據簽名軟件)	Qijie Technology	2024SR1268758	PRC
9.	Qijie Digital Enterprise Chip Product File Management System Software (旗捷數字企業芯片產品檔案管理系統軟件)	Qijie Technology	2023SR1233108	PRC

No.	Software	Owner	Registration Number	Place of Registration
10.	Qijie Data Analysis and Classification Software for Hardware Security Communication (旗捷硬件安全領域通信的數據解析分類軟件)	Qijie Technology	2023SR1479937	PRC
11.	Qijie Logic Analyzer IIC Protocol Exported Text Analysis Software (旗捷邏輯分析儀IIC協議導出文本解析軟件)	Qijie Technology	2022SR0092009	PRC
12.	Qijie Communication Software with Encryption Chip (旗捷與加密芯片通訊軟件)	Qijie Technology	2022SR0092007	PRC
13.	Qijie CJ28E22 Burning Software (旗捷CJ28E22燒錄軟件)	Qijie Technology	2022SR1076775	PRC
14.	Qijie Digital Factory APP Software (旗捷數字化工廠APP軟件)	Qijie Technology	2022SR1427456	PRC
15.	Qijie Intelligent Cloud Upgrade Terminal Software (旗捷智能雲升級終端軟件)	Qijie Technology	2021SR1133272	PRC
16.	Qijie RFID Printing Consumable Chip Communication Protocol Analysis Software (旗捷RFID打印耗材芯片通信協議分析軟件)	Qijie Technology	2020SR1577646	PRC
17.	Qijie Printing Consumable Chip Communication Protocol Analysis Software (旗捷打印耗材芯片通信協議分析軟件)	Qijie Technology	2020SR1570031	PRC
18.	Qijie Inkjet Printing Consumable Chip Communication Analysis Software (旗捷噴墨打印耗材芯片通信分析軟件)	Qijie Technology	2020SR1570032	PRC

No.	Software	Owner	Registration Number	Place of Registration
19.	Qijie Laser Printing Consumable Chip Control Software (旗捷激光打印耗材芯片控制軟件)	Qijie Technology	2017SR429062	PRC
20.	Qijie Printing Consumable Chip Communication Software Based on I2C Protocol (旗捷基於I2C協議的打印耗材芯片通信軟件)	Qijie Technology	2017SR434489	PRC
21.	Regenerative Printing Initial Data Reset and Rewrite Software of Qijie (旗捷再生式打印初始數據復位改寫軟件)	Qijie Technology	2016SR090007	PRC
22.	Qijie Fifty-piece Consumable Reader-writer Control Software (旗捷五十連片耗材寫讀碼儀控制軟件)	Qijie Technology	2016SR089597	PRC
23.	Qijie Regenerative Printing Data Detection and Rewriting Software (旗捷再生式打印數據檢測改寫軟件)	Qijie Technology	2016SR322430	PRC
24.	Qijie Printing Consumable Chip Communication Software Based on I2C Protocol (旗捷基於I2C協議的打印耗材芯片通信軟件)	Qijie Technology	2016SR322275	PRC
25.	Qijie Printing Consumable Chip Single-wire Communication Protocol Software (旗捷打印耗材芯片單線通信協議軟件)	Qijie Technology	2016SR321759	PRC
26.	Qijie Printing Consumable Chip Remote Data Update Software (旗捷打印耗材芯片數據遠程更新軟件)	Qijie Technology	2016SR345707	PRC
27.	Qijie Regenerative Printing Initial Data Reset and Rewrite Software (旗捷再生式打印初始數據復位改寫軟件)	Qijie Technology	2016SR345941	PRC

No.	Software	Owner	Registration Number	Place of Registration
28.	Qijie Printing Consumable Chip Control Software (旗捷打印耗材芯片控制軟件)	Qijie Technology	2012SR000803	PRC
29.	Sensor Circuit Detection Software for Qijie Printing Consumable Chips (旗捷打印耗材芯片的傳感器電路檢測軟件)	Qijie Technology	2012SR028000	PRC
30.	Qijie Print Consumable Chip Simulation Test Software (旗捷打印耗材芯片仿真測試軟件)	Qijie Technology	2012SR027996	PRC
31.	External Initial Data Reset Software for Qijie Printing Consumable Chips (旗捷打印耗材芯片外置式初始數據復位軟件)	Qijie Technology	2012SR027990	PRC
32.	Online Initial Data Recovery Software for Qijie Printing Consumable Chips (旗捷打印耗材芯片在線式初始數據恢復軟件)	Qijie Technology	2012SR027993	PRC
33.	Qijie Consumable Coding Instrument Control Software (旗捷耗材寫碼儀控制軟件)	Qijie Technology	2009SR031871	PRC
34.	Qijie Consumable Detector Control Software (旗捷耗材檢測儀控制軟件)	Qijie Technology	2009SR031872	PRC
35.	Qijie Ten-piece Consumable Coding Instrument Control Software (旗捷十連片耗材寫碼儀控制軟件)	Qijie Technology	2009SR031875	PRC
36.	Qijie Printing Consumables Chip Control Software (旗捷打印耗材芯片控制軟件)	Qijie Technology	2008SR18258	PRC
37.	Qijie Printing Consumables Chip Control Software (旗捷打印耗材芯片控制軟件)	Qijie Technology	2007SR13788	PRC

(iv) Domain Name

As of the Latest Practicable Date, we owned the following domain name which we consider to be or may be material to our business:

No.	Domain Name	Owner
1.	www.dl-kg.com	Our Company

C. FURTHER INFORMATION ABOUT OUR DIRECTORS, CHIEF EXECUTIVE AND SUBSTANTIAL SHAREHOLDERS

1. Disclosure of Interests of the Directors and Chief Executive

The following sets out the interests of our Directors and chief executive of our Company immediately following the completion of the [REDACTED] (assuming (i) the [REDACTED] is not exercised, and (ii) no other changes are made to the total issued share capital of our Company since the Latest Practicable Date and up to the [REDACTED], and excluding any A Shares may be issued upon conversion of the Convertible Bonds) in the Shares of our Company or any of our associated corporations (within the meaning of Part XV of the SFO) which will have to be notified to us and the Stock Exchange pursuant to Divisions 7 and 8 of Part XV of the SFO (including interests and short positions in which they are taken or deemed to have under such provisions of the SFO), or which will be required, pursuant to section 352 of the SFO, to be entered in the register referred to therein, or which will be required to be notified to us and the Stock Exchange pursuant to the Model Code for Securities Transactions by Directors of Listed Issuers contained in the Listing Rules:

(i) Interests in Our Company

Name	Positions	Nature of Interests	Number and Description of Shares	Approximate Percentage of Interests in our Company Immediately Following the Completion of the [REDACTED]
Mr. Zhu Shuangquan(1)	Chairman of the Board and executive Director	Beneficial owner	139,249,514 A Shares	[REDACTED]%
		Interest of person acting in concert	138,031,414 A Shares	[REDACTED]%
Mr. Zhu Shunquan(1)	Executive Director and general manager	Beneficial owner	138,031,414 A Shares	[REDACTED]%
		Interest of person acting in concert	139,249,514 A Shares	[REDACTED]%

Name	Positions	Nature of Interests	Number and Description of Shares	Approximate Percentage of Interests in our Company Immediately Following the Completion of the [REDACTED]
Ms. Yao Hong[(2)]	Executive Director and chief financial officer	Beneficial owner	381,250 A Shares	[REDACTED]%
Ms. Yang Pingcai[(3)]	Executive Director, deputy general manager and Board secretary	Beneficial owner	442,500 A Shares	[REDACTED]%
Dr. Yang Bo	Non-executive Director	Beneficial owner	560,084 A Shares	[REDACTED]%
Mr. Luo Deri[(4)]	Non-executive Director and employee representative Director	Beneficial owner	114,630 A Shares	[REDACTED]%

Notes:

(1) For details of the interests held by Mr. Zhu Shuangquan and Mr. Zhu Shunquan, see "Substantial Shareholders."

(2) As of the Latest Practicable Date, Ms. Yao Hong (i) directly held 306,250 A Shares of our Company, and (ii) was entitled to subscribe for 75,000 A Shares of our Company pursuant to the stock options granted to her under the 2024 Stock Option Incentive Plan, subject to the conditions thereof.

(3) As of the Latest Practicable Date, Ms. Yang Pingcai (i) directly held 327,500 A Shares of our Company, and (ii) was entitled to subscribe for 115,000 A Shares of our Company pursuant to the stock options granted to her under the 2024 Stock Option Incentive Plan, subject to the conditions thereof.

(4) As of the Latest Practicable Date, Mr. Luo Deri (i) directly held 84,630 A Shares of our Company, and (ii) was entitled to subscribe for 30,000 A Shares of our Company pursuant to the stock options granted to him under the 2024 Stock Option Incentive Plan, subject to the conditions thereof.

2. Disclosure of Interests of the Substantial Shareholders

(i) Interests in Our Company

Save as disclosed in the section headed "Substantial Shareholders," immediately following the completion of the [REDACTED] (assuming (i) the [REDACTED] is not exercised, and (ii) no other changes are made to the total issued share capital of our Company since the Latest Practicable Date and up to the [REDACTED], and excluding any A Shares may be issued upon conversion of the Convertible Bonds), our Directors are not aware of any other person (not being a Director or chief executive of our Company) who would have an interest or short position in the Shares or the underlying Shares which would fall to be disclosed to us and the Stock Exchange under the provisions of Divisions 2 and 3 of Part XV of the SFO, or be interested, directly or indirectly, in 10% or more of the nominal value of any class of share capital carrying rights to vote in all circumstances at general meetings of our Company.

(ii) Interests in Other Members of Our Group

So far as our Directors are aware, as of the Latest Practicable Date, the following persons (other than members of our Group, the Directors or chief executive of our Company) were interested in 10% or more of the nominal value of any class of share capital carrying rights to vote in all circumstances at general meetings of members of our Group:

Name of Member of our Group	Name of Substantial Shareholder	Approximate Percentage of Voting Rights Held by Substantial Shareholder
Hao Fei	Hou Lingling (侯玲玲)	15.86%
Dingze New Materials Technology	TOPSCIENCE TECHNOLOGY PTE. LTD.	10.00%
Dinglong (Qianjiang) New Materials	Ningbo Baicheng Enterprise Management Partnership (Limited Partnership) (寧波百誠企業管理合夥企業(有限合夥))	10.53%
	Ningbo Jinghe Enterprise Management Partnership (Limited Partnership) (寧波晶和企業管理合夥企業(有限合夥))	10.53%
Hubei Dingying Materials Technology Co., Ltd. (湖北鼎英材料科技有限公司)	Wuhan Yuxinheng Enterprise Management Partnership (Limited Partnership) (武漢欲信恒企業管理合夥企業(有限合夥))	27.14%

Name of Member of our Group	Name of Substantial Shareholder	Approximate Percentage of Voting Rights Held by Substantial Shareholder
Zhejiang Zhiyi Semiconductor Co., Ltd. (浙江執一半導體有限公司)	Ningbo Jingyi Qiujing Self-funded Investment Partnership (Limited Partnership) (寧波晶亦求晶自有資金投資合夥企業(有限合夥))	29.00%
	Wang Zhiping (王志萍)	20.00%

3. Particulars of Service Contracts

Our Company [has entered] into a service contract with each of the Directors. The principal particulars of these service contracts are: (i) each of the contracts is for a term of three years following the commencement date of his/her term of office; and (ii) each of the contracts is subject to termination in accordance with their respective terms. The service contracts may be renewed in accordance with our Articles of Association and the applicable laws, rules and regulations from time to time.

Save as disclosed above, our Directors have not entered into or proposed to enter into any service contracts with any member of our Group (other than contracts expiring or determinable by the employer within one year without the payment of compensation (other than statutory compensation).

4. Directors' Remuneration

Save as disclosed in "Directors and Senior Management" of this document and Note 10 to the Accountants' Report as set out in Appendix I to this document, for the years ended December 31, 2023, 2024 and 2025 and the four months ended April 30, 2026, none of our Directors received other remunerations or benefits in kind from us.

5. Disclaimers

Save as disclosed in this Appendix, none of the Directors of our Company or any of the parties listed in "— E. Other Information — 7. Qualifications and Consents of Experts" in this Appendix:

(i) is interested in our promotion, or in any assets which, within the two years immediately preceding the date of this document, have been acquired or disposed of by or leased to us, or are proposed to be acquired or disposed of by or leased to our Company; or

(ii) is materially interested in any contract or arrangement subsisting at the date of this document that is significant in relation to our Company's business.

D. 2024 STOCK OPTION INCENTIVE PLAN

The following is a summary of the principal terms of the 2024 Stock Option Incentive Plan which was in effect as of the Latest Practicable Date. The terms of 2024 Stock Option Incentive Plan do not involve any grant of share incentives by our Company after the [REDACTED] and are not subject to the provisions of Chapter 17 of the Listing Rules.

1. Purpose

The purpose of the 2024 Stock Option Incentive Plan is to establish and enhance our Company's long-term incentive mechanism, attract and retain outstanding talent, and fully motivate our Directors, senior management, core technical and managerial personnel by aligning the interests of our Shareholders, our Company and the core team members, thereby supporting the long-term development of our Company while safeguarding Shareholders' interests and linking rewards to performance and contribution.

2. Administration

The 2024 Stock Option Incentive Plan is subject to approval by our general meeting and will be implemented and administered by the Board. The Remuneration and Appraisal Committee is responsible for formulating and revising the 2024 Stock Option Incentive Plan and submitting it to the Board for consideration.

3. Eligible Participants

The eligible participants of the 2024 Stock Option Incentive Plan include Directors, senior management members, and core technical and managerial personnel of our Company, but do not include (i) independent non-executive Directors, (ii) Shareholder who, individually or in aggregate, holds 5% or more of the Shares of our Company, or actual controller(s) and their respective spouse, parents and children, and (iii) foreign employees. All eligible participants must maintain an employment or service relationship with our Company or its subsidiaries during the term of the 2024 Stock Option Incentive Plan.

4. Source and Maximum Number of Shares

The underlying Shares for the 2024 Stock Option Incentive Plan shall be A Shares to be issued by our Company to the eligible participants.

Subject to the adjustment mechanisms pursuant to the scheme rules, the maximum number of Shares initially available to be granted under the 2024 Stock Option Incentive Plan was 25,000,000 A Shares. The number of Shares granted to any individual grantee under all the share incentive plans of our Company currently in effect shall not exceed 1% of our Company's total share capital.

5. Date of Grant and Duration

The date of grant of the stock options shall be a trading day of the Shenzhen Stock Exchange determined by the Board within 60 days after the 2024 Stock Option Incentive Plan is approved at the general meeting. The grant of stock options shall be approved by the Board, and the relevant registration and announcement procedures shall be completed within such 60-day period.

The 2024 Stock Option Incentive Plan shall be effective from the date of grant of the options up to the date on which all stock options granted thereunder have been exercised or cancelled, provided that the term of the 2024 Stock Option Incentive Plan shall not exceed 48 months.

6. Vesting and Exercise Schedule

The vesting period for stock options shall commence from the grant date of the stock options to the date on which the stock options become exercisable. The vesting periods for the stock options under the 2024 Stock Option Incentive Plan are 12 months, 24 months and 36 months from the date of grant, with 40%, 30% and 30% of the granted stock options vesting at the end of the respective periods. During the vesting period, the stock options granted to the participants under the Stock Option Incentive Plan shall not be transferred, used for guarantee or repayment of debts.

The stock options will become exercisable after the vesting period in accordance with the exercise schedule as set out below and the conditions set out under paragraph 9 are fulfilled:

Tranche	**Exercise Period**	**Proportion**
First Exercise Period	From the first trading day after the expiry of 12 months from the date of grant to the last trading day falling within 24 months from the date of grant, both dates inclusive	40%
Second Exercise Period	From the first trading day after the expiry of 24 months from the date of grant to the last trading day falling within 36 months from the date of grant, both dates inclusive	30%
Third Exercise Period	From the first trading day after the expiry of 36 months from the date of grant to the last trading day falling within 48 months from the date of grant, both dates inclusive	30%

The exercise of the stock options granted shall be on a trading day of the Shenzhen Stock Exchange, which shall not fall within any prohibited period stipulated by the CSRC and the Shenzhen Stock Exchange. Where a grantee fails to exercise any stock options within the above prescribed period, or where the stock options for the relevant tranche cannot be exercised as the exercise conditions have not been satisfied, our Company shall cancel the corresponding unexercised stock options of such grantee in accordance with the terms of the 2024 Stock Option Incentive Plan, and the relevant rights and interests shall not be carried forward to any subsequent period.

7. Lock-up Arrangements

The lock-up arrangements under the 2024 Stock Option Incentive Plan are determined in accordance with the applicable PRC laws and regulations and the Articles of Association:

(i) if the grantee is a Director or a senior management member of the Company, the Shares to be transferred each year during his/her tenure shall not exceed 25% of the total Shares held by him/her. No Shares held by such Director or senior management member may be transferred within six months after termination of his/her employment; and

(ii) in the event of any changes to the applicable laws and regulations or the relevant provisions of the Articles of Association on the foregoing lock-up requirements within the term of the 2024 Stock Option Incentive Plan, the grantee shall comply with such amended requirements.

8. Exercise Price

The exercise price of each stock option under the 2024 Stock Option Incentive Plan shall be no less than the nominal value of each A Share, and, in principle, shall be no less than the higher of:

(i) the average trading price of the A Shares on the trading day immediately preceding the announcement of the 2024 Stock Option Incentive Plan; and

(ii) the average trading price of the A Shares during the 60 trading days immediately preceding the announcement of the 2024 Stock Option Incentive Plan.

9. Conditions for the Grant and Exercise of Stock Options

The stock options will only be granted to the participants if the following conditions are fulfilled:

(i) With respect to our Company, none of the following circumstances having occurred:

(a) an audit report with an adverse opinion or a disclaimer of opinion has been issued by the certified public accountant with respect to our accountant's report for the most recent fiscal year;

(b) an audit report with an adverse opinion or a disclaimer of opinion has been issued by the certified public accountant with respect to the internal control report contained in accountant's report for the most recent fiscal year;

(c) failure to distribute profits in accordance with laws and regulations, the Articles of Association, or public commitments within the last 36 months after its listing on the Shenzhen Stock Exchange; and

(d) prohibition from the implementation of share incentive schemes by applicable laws and regulations; or

(e) any other circumstances as determined by the CSRC.

(ii) With respect to the grantee, none of the following circumstances having occurred:

(a) the grantee has been regarded as an inappropriate person by the Shenzhen stock exchange within the last 12 months;

(b) the grantee has been regarded as an inappropriate person by the CSRC or its local office within the last 12 months;

(c) the grantee has been subject to administrative penalties or market ban measures by the CSRC or its local office due to material violations of laws and regulations within the last 12 months;

(d) the grantee is not qualified to serve as a Director or senior management member under the PRC Company Law; and

(e) the grantee is prohibited from participating in share incentive schemes of listed companies under laws and regulations; or

(f) any other circumstances as determined by the CSRC.

In order for the stock options to become exercisable, in addition to the conditions set out above, the grantee shall also satisfy the performance targets in accordance with the terms of the 2024 Stock Option Incentive Plan.

10. Adjustments

Subject to the other terms and conditions of the 2024 Stock Option Incentive Plan and applicable laws and regulations, if our Company undertakes any capitalization of capital reserve, bonus issue, share subdivision, rights issue, share consolidation or dividend distribution before the exercise of the stock options, the number of stock options and/or the exercise price shall be adjusted accordingly, as applicable.

11. Outstanding Stock Options

As of the Latest Practicable Date, the number of outstanding stock options granted under the 2024 Stock Option Incentive Plan was 9,280,611, representing approximately [REDACTED]% of the issued Shares immediately following the completion of the [REDACTED] (assuming (i) the [REDACTED] is not exercised, and (ii) no other changes are made to the total issued share capital of our Company since the Latest Practicable Date and up to the [REDACTED], and excluding any A Shares may be issued upon conversion of the Convertible Bonds). If all such outstanding stock options are fully exercised, assuming the [REDACTED] is not exercised and no other changes are made to the issued share capital of our Company between the Latest Practicable Date and the [REDACTED], the issued and outstanding Shares held by Shareholders immediately following the [REDACTED] will be diluted by approximately [REDACTED]%. The dilutive effect on our earnings per Share will be approximately [REDACTED]%.

The following table sets forth the details of the outstanding stock options granted to all grantees (including Directors, senior management members, connected persons and other employees of our Company) under the 2024 Stock Option Incentive Plan as of the Latest Practicable Date. No consideration is paid/payable by the eligible participants for the grant of stock options under the 2024 Stock Option Incentive Plan.

Name of the Grantee	Positions/connected relationships	Date of Grant	Address	Number of A Shares Underlying the Outstanding Stock Options	Exercise Price (per Share)	Exercise Period	Approximate Percentage of Issued Shares Immediately After the [REDACTED][1]
Directors or Senior Management Members							
Ms. Yao Hong	Executive Director and chief financial officer	May 16, 2024	4002, Unit 1, Building 3, Phase II, Feicui City, Changfeng Subdistrict, Qiaokou District, Wuhan, Hubei Province, the PRC	75,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Ms. Yang Pingcai	Executive Director, deputy general manager and Board secretary	May 16, 2024	No. 18–2, Area 2, Liqiao Village, Hongshan District, Wuhan, Hubei Province, the PRC	115,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Luo Deri	Non-executive Director and employee representative Director	May 16, 2024	No. 95 Baixing Street, Xu Zhen, Wanhe Town, Taihe County, Ji'an, Jiangxi Province, the PRC	30,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%*
Mr. Huang Jinhui	Deputy general manager	May 16, 2024	Room 1, 6/F, No. 536–2 Jianshe Avenue, Jianghan District, Wuhan, Hubei Province, the PRC	150,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Dr. Xiao Guilin	Deputy general manager	May 16, 2024	No. 16 Luojiashan, Wuchang District, Wuhan, Hubei Province, the PRC	150,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Connected Persons							
Ms. Lu Liping	*Note 2*	May 16, 2024	Room 802, Unit 1, Building 7, China Merchants Park Jingyuan, No. 288 Jiangcheng Avenue, Hanyang District, Wuhan, Hubei Province, the PRC	180,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Wang Zhiping	*Note 2*	May 16, 2024	Room 718, Building 3, Hangyue Commercial Center, Hangzhou, Zhejiang Province, the PRC	174,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%

Name of the Grantee	Positions/connected relationships	Date of Grant	Address	Number of A Shares Underlying the Outstanding Stock Options	Exercise Price (per Share)	Exercise Period	Approximate Percentage of Issued Shares Immediately After the [REDACTED](1)
Ms. Zhou Yi	*Note 2*	May 16, 2024	Room 1804, Unit 1, Building 7, Chunfengli, Zhuhai Shuiyun Garden, Xianlin Subdistrict, Yuhang District, Hangzhou, Zhejiang Province, the PRC	107,033	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Wang Lei	*Note 2*	May 16, 2024	No. 1 Dongjinghe Road, Hanyang District, Wuhan, Hubei Province, the PRC	90,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. He Kang	*Note 2*	May 16, 2024	No. 110–0501 Shouyi Road, Wuchang District, Wuhan, Hubei Province, the PRC	88,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Liu Min	*Note 2*	May 16, 2024	No. 29 Baiye Road, Hanyang District, Wuhan, Hubei Province, the PRC	75,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Ren Jilin	*Note 2*	May 16, 2024	Room 301, Unit 3, Building 33, Tongxin Garden, Jiang'an District, Wuhan, Hubei Province, the PRC	60,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Wang Bin	*Note 2*	May 16, 2024	Room 4103, 41/F, Unit 1, Building 16, No. 584 Jiefang Avenue, Qiaokou District, Wuhan, Hubei Province, the PRC	60,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Ms. Wang Zhangyan	*Note 2*	May 16, 2024	Room 601, Unit 1, Building 13, Yijia Tangcheng, Jiangxia Avenue, Miaoshan Development Zone, Jiangxia District, Wuhan, Hubei Province, the PRC	60,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Zhou Bo	*Note 2*	May 16, 2024	Room 2004, Unit 1, Building F2, Vanke Jinyu Lanwan, No. 35 Sanjiaohu Road, Hanyang District, Wuhan, Hubei Province, the PRC	60,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%

Name of the Grantee	Positions/connected relationships	Date of Grant	Address	Number of A Shares Underlying the Outstanding Stock Options	Exercise Price (per Share)	Exercise Period	Approximate Percentage of Issued Shares Immediately After the [REDACTED](1)
Ms. Dai Yuanzheng	*Note 2*	May 16, 2024	Room 3, 6/F, No. 27–1, Wansong Community, Jianghan District, Wuhan, Hubei Province, the PRC	54,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Mr. Su Minguang	*Note 2*	May 16, 2024	No. 271 Zhuodaoquan Road, Hongshan District, Wuhan, Hubei Province, the PRC	45,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%*
Ms. Liu Wei	*Note 2*	May 16, 2024	Room 2, Unit 2, Building 2, No. 5 Yeting Road, Enshi, Hubei Province, the PRC	26,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%*
Mr. Huang Chuanling	*Note 2*	May 16, 2024	No. 2 Sanyi Road, Changsha County, Hunan Province, the PRC	22,500	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%*
Mr. Liang Fei	*Note 2*	May 16, 2024	Room 1403, Unit 1, Building 57, No. 8 Baishazhou Avenue, Hongshan District, Wuhan, Hubei Province, the PRC	10,500	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%*
Other Employees							
255 other employees in aggregate	Core technical and managerial personnel	May 16, 2024	—	7,648,578	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Total				**9,280,611**			**[REDACTED]%**

Notes:

(1) Assuming (i) the [REDACTED] is not exercised, and (ii) no other changes are made to the total issued share capital of our Company since the Latest Practicable Date and up to the [REDACTED], and excluding any A Shares may be issued upon conversion of the Convertible Bonds.

(2) All being directors, chief executives, supervisors or former directors in the last 12 months of our subsidiaries and therefore constituting connected persons within the meaning of Chapter 14A of the Listing Rules.

* *Denotes less than [REDACTED]%*

The following table sets forth the details of the outstanding stock options granted to other grantees (excluding Directors, senior management members and connected persons of our Company) under the 2024 Stock Option Incentive Plan as of the Latest Practicable Date.

Range of Outstanding Stock Options	Date of Grant	Number of Grantees	Number of A Shares Underlying the Outstanding Stock Options	Exercise Price (per Share)	Exercise Period	Approximate Percentage of Issued Shares Immediately After the [REDACTED][(1)]
1–10,000	May 16, 2024	60	459,000	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
10,001–50,000	May 16, 2024	154	3,939,863	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
>50,000	May 16, 2024	41	3,249,715	RMB18.83	May 16, 2025 to May 15, 2028	[REDACTED]%
Total		**255**	**7,648,578**			**[REDACTED]%**

Note:

(1) Assuming (i) the [REDACTED] is not exercised, and (ii) no other changes are made to the total issued share capital of our Company since the Latest Practicable Date and up to the [REDACTED], and excluding any A Shares may be issued upon conversion of the Convertible Bonds.

E. OTHER INFORMATION

1. Estate Duty

Our Directors have been advised that no material liability for estate duty is likely to be imposed on our Company or any of the subsidiaries of our Company.

2. Litigation

As of the Latest Practicable Date, we were not aware of any other litigation or arbitration proceedings of material importance pending or threatened against us or any of our Directors that would have a material adverse effect on our financial condition or results of operations.

3. Joint Sponsors

The Joint Sponsors satisfy the independence criteria applicable to sponsors set out in Rule 3A.07 of the Listing Rules. The Joint Sponsors will in aggregate be paid by our Company a fee of RMB3 million to act as sponsors to our Company in connection with the [REDACTED].

The Joint Sponsors have applied to the Stock Exchange for the [REDACTED] of, and permission to [REDACTED], our H Shares to be [REDACTED] pursuant to the [REDACTED]. All necessary arrangements [have been] made enabling the H Shares to be admitted into [REDACTED].

4. Preliminary Expenses

Our Company did not incur any material preliminary expenses.

5. No Material Adverse Change

Our Directors confirm that there has been no material adverse change in the financial or trading position or prospects of our Group since April 30, 2026 (being the date to which the latest consolidated financial statements of our Group were prepared).

6. Promoters

The promoters of our Company are as follows:

No.	Name
1.	Zhu Shuangquan (朱雙全)
2.	Zhu Shunquan (朱順全)
3.	Li Lin (李林)
4.	Wang Bin (王斌)
5.	Huang Jinhui (黃金輝)
6.	Lan Zeguan (蘭澤冠)
7.	Yang Bo (楊波)
8.	Zeng Ailian (曾愛蓮)
9.	Zuo Xinju (左新舉)
10.	Lu Liping (魯麗平)
11.	Li Dongsheng (李冬生)
12.	Chen Xi (陳曦)
13.	Liang Jue (梁珏)
14.	Liu Shengrong (劉勝榮)
15.	Dai Yuanzheng (戴遠征)
16.	Rao Feng (饒峰)
17.	Zhu Xianmin (朱獻民)
18.	Wang Yubin (王玉賓)
19.	Song Jun (宋軍)
20.	Tian Mei (田梅)
21.	Tian Kaijun (田凱軍)
22.	China Bao'an Group Holding Co., Ltd. (中國寶安集團控股有限公司)
23.	Shenzhen Capital Group Co., Ltd. (深圳市創新投資集團有限公司)
24.	Hubei Provincial High and New Technology Industrial Investment Co., Ltd. (湖北省高新技術產業投資有限公司)
25.	Wuhan Science and Technology Innovation Investment Co., Ltd. (武漢科技創新投資有限公司)
26.	China Venture Capital Co., Ltd. (中國風險投資有限公司)

Within the two years immediately preceding the date of this document, no cash, securities or other benefit has been paid, allotted or given nor are any proposed to be paid, allotted or given to any promoters in connection with the [REDACTED] and the related transactions described in this document.

7. Qualifications and Consents of Experts

The following are the qualifications of the experts who have given and have not withdrawn their consents to the issue of this document with the inclusion of their report, letter, summary of valuations, valuation certificates and/or legal opinion (as the case may be) and references to their names included in the form and context in which they respectively appear:

Name	Qualification
China Merchants Securities (HK) Co., Limited	A licensed corporation under the SFO to conduct Type 1 (dealing in securities), Type 2 (dealing in futures contracts), Type 4 (advising on securities), Type 6 (advising on corporate finance) and Type 9 (asset management) of regulated activities as defined under the SFO
CITIC Securities (Hong Kong) Limited	A licensed corporation under the SFO to conduct Type 4 (advising on securities) and Type 6 (advising on corporate finance) of regulated activities as defined under the SFO
BDO Limited	Certified Public Accountants and Registered Public Interest Entity Auditor
Hunan Qiyuan Law Firm	Legal advisors to our Company as to PRC law
Frost & Sullivan (Beijing) Inc., Shanghai Branch Co.	Independent industry consultant
King and Wood LLP	Legal advisors to our Company as to international sanctions laws

As of the Latest Practicable Date, save as in connection with the [REDACTED], none of the experts named above is interested legally or beneficially in any shares of any member of our Group or has any right (whether legally enforceable or not) to subscribe for or to nominate persons to subscribe for securities in any member of our Group.

8. Binding Effect

This document shall have the effect, if any application is made pursuant hereto, of rendering all persons concerned bound by all the provisions (other than the penal provisions) of sections 44A and 44B of the Companies (Winding Up and Miscellaneous Provisions) Ordinance so far as applicable.

9. Bilingual Document

The English language and Chinese language versions of this document are being published separately, in reliance upon the exemption provided by section 4 of the Companies Ordinance (Exemption of Companies and Prospectuses from Compliance with Provisions) Notice (Chapter 32L of the Laws of Hong Kong). In case of any discrepancies between the English language version and Chinese language version of this document, the English language version shall prevail.

10. Taxation of Holders of H Shares

The sale, purchase and transfer of H Shares are subject to Hong Kong stamp duty if such sale, purchase and transfer are effected on the H Share register of members of our Company, including in circumstances where such transactions are effected on the Stock Exchange. The current rate of Hong Kong stamp duty for such sale, purchase and transfer is 0.1% of the consideration or, if higher, the fair value of the H Shares being sold or transferred, payable by each of the purchaser and the seller.

11. Miscellaneous

Save as disclosed in the sections headed "History and Corporate Structure", "Financial Information" and this Appendix or in connection with the [REDACTED],

(i) within the two years immediately preceding the date of this document, to the best of our knowledge,

  (a) neither our Company nor any of our subsidiaries has issued or agreed to issue any share or loan capital fully or partly paid up either for cash or for a consideration other than cash; and

  (b) no commissions, discounts, brokerage fee or other special terms have been granted in connection with the issue or sale of any share or loan capital of our Company or any of our subsidiaries;

(ii) no share or loan capital of our Company or any of our subsidiaries is under option or is agreed conditionally or unconditionally to be put under option;

(iii) no commission has been paid or is payable for subscribing or agreeing to subscribe, or procuring or agreeing to procure the subscriptions of any share in our Company or any of our subsidiaries;

(iv) there are no arrangements under which future dividends are waived or agreed to be waived;

(v) there have been no interruptions in our business which may have or have had a significant effect on our financial position in the 12 months preceding the date of this document; and

(vi) our Company has no outstanding convertible debt securities or debentures.